

HIGH-TEMPERATURE SCANNING INDENTATION: A NEW TECHNIQUE TO ASSESS MICROSTRUCTURAL CHANGES ALONG THERMAL RAMPING

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Thanks to recent developments in high temperature nanoindentation testing, investigation of thermally activated mechanisms at small length scales can now be carried out [1]. *In-situ* anisothermal measurements at the micron-scale of hardness, Young modulus and creep properties are now feasible. The development of the High Temperature Scanning Indentation [2] technique, based on a specific high-speed loading procedure, allows quasi-continuous determination of those properties in temperature in only few hours.

We focus here on cold-rolled pure aluminum (see figure) that undergoes static recovery and recrystallization during an annealing thermal cycle: Hardness upon heating and cooling varies in a different manner, pointing out the occurrence of those phenomena upon heating. Part of the observed hardness drop was related to recrystallization, assessed by post-mortem EBSD microstructural characterizations. Moreover, such methodology allows to determine creep properties. Such information leads to the determination of creep activation energy of those samples.

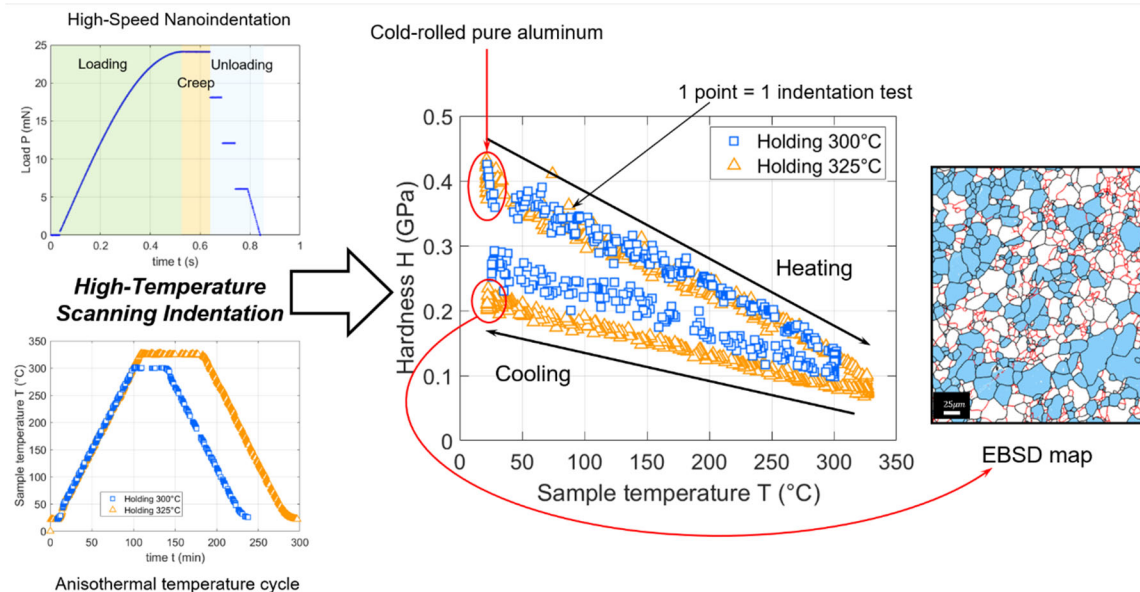


Figure 1 - HTSI method used on cold-rolled pure aluminum samples. Hardness evolution during the thermal cycle shows the microstructure changes, from [2].

[1] Baral et al., Materials and Design, (2018)

[2] Tiphène et al., Journal of Material Research, (2021)